



WIDEBAND, LOW NOISE, LOW DISTORTION FULLY DIFFERENTIAL AMPLIFIER WITH RAIL-TO-RAIL OUTPUTS

FEATURES

- Fully Differential Architecture With Rail-to-Rail Outputs
- Centered Input Common-mode Range
- Minimum Gain of 1 V/V (0 dB)
- Bandwidth: 620 MHz
- Slew Rate: 570 V/ μ s
- 0.1% Settling Time: 7 ns
- HD_2 : -115 dBc at 100 kHz, $V_{OD} = 8 V_{PP}$
- HD_3 : -123 dBc at 100 kHz, $V_{OD} = 8 V_{PP}$
- Input Voltage Noise: 2 nV/ $\sqrt{Hz}$ ($f > 10$ kHz)
- Output Common-Mode Control
- Power Supply:
 - Voltage: 3.3 V (± 1.5 V) to 5 V (± 2.5 V)
 - Current: 14.2 mA
- Power-Down Capability: 15 μ A

APPLICATIONS

- 5-V and 3.3-V Data Acquisition Systems
- High Linearity ADC Amplifier
- Wireless Communication
- Test and Measurement
- Voice Processing Systems

RELATED PRODUCTS

Device	BW (MHz)	Slew Rate (V/ μ sec)	THD (dBc)	V_N (nV/ $\sqrt{Hz}$)
THS4509	2000	6600	-102 at 10 MHz	1.9
THS4500	370	2800	-82 at 8 MHz	7
THS4130	150	52	-97 at 250 kHz	1.3

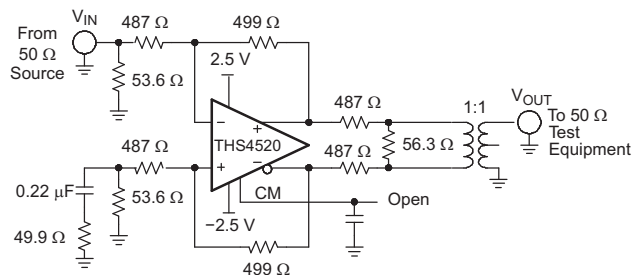
DESCRIPTION

The THS4520 is a wideband, fully differential operational amplifier designed for 5-V data acquisition systems. It has very low noise at 2 nV/ $\sqrt{Hz}$, and low harmonic distortion of -115 dBc HD_2 and -123 dBc HD_3 at 100 kHz with 8 V_{PP} , and 1-k Ω load. The slew rate is 570 V/ μ s, and with a settling time of 7 ns to 0.1% (2-V step), it is ideal for data acquisition applications. It is designed for unity gain stability.

To allow for dc coupling to ADCs, its unique output common-mode control circuit maintains the output common-mode voltage within 0.25 mV offset (typical) from the set voltage. The common-mode set point defaults to mid-supply by internal circuitry, which may be over-driven from an external source.

The input and output are optimized for best performance with their common-mode voltages set to mid-supply. Along with high performance at low power supply voltage, this makes for extremely high performance single supply 5-V and 3.3-V data acquisition systems.

The THS4520 is offered in a Quad 16-pin leadless QFN package (RGT), and is characterized for operation over the full industrial temperature range from -40°C to 85°C.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

ABSOLUTE MAXIMUM RATINGS

over operating free-air temperature range (unless otherwise noted)

		UNIT
V_{S-} to V_{S+}	Supply voltage	6 V
V_I	Input voltage	$\pm V_S$
V_{ID}	Differential input voltage	4 V
I_O	Output current ⁽¹⁾	200 mA
Continuous power dissipation		See Dissipation Rating Table
T_J	Maximum junction temperature	150°C
	Maximum junction temperature, continuous operation, long term reliability	125°C
T_A	Operating free-air temperature range	–40°C to 85°C
T_{stg}	Storage temperature range	–65°C to 150°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds		300°C
ESD ratings	HBM	2000
	CDM	1500
	MM	100

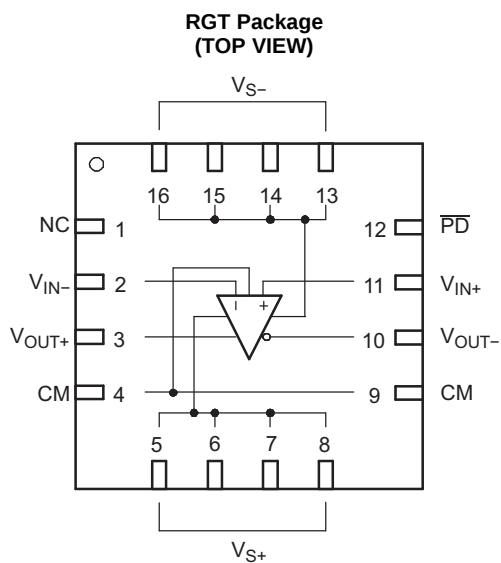
- (1) The THS4520 incorporates a (QFN) exposed thermal pad on the underside of the chip. See TI technical brief [SLMA002](#) and [SLMA004](#) for more information about utilizing the QFN thermally enhanced package.

DISSIPATION RATINGS TABLE PER PACKAGE

PACKAGE ⁽¹⁾	θ_{JC}	θ_{JA}	POWER RATING	
			$T_A \leq 25^\circ\text{C}$	$T_A = 85^\circ\text{C}$
RGT (16)	2.4°C/W	39.5°C/W	2.3 W	225 mW

- (1) For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI Web site at www.ti.com.

DEVICE INFORMATION



TERMINAL FUNCTIONS

TERMINAL (RGT PACKAGE)		DESCRIPTION
NO.	NAME	
1	NC	No internal connection
2	V _{IN-}	Inverting amplifier input
3	V _{OUT+}	Non-inverted amplifier output
4, 9	CM	Common-mode voltage input
5, 6, 7, 8	V _{S+}	Positive amplifier power supply input
10	V _{OUT-}	Inverted amplifier output
11	V _{IN+}	Non-inverting amplifier input
12	$\overline{\text{PD}}$	Powerdown, $\overline{\text{PD}}$ = logic low puts part into low power mode, $\overline{\text{PD}}$ = logic high or open for normal operation. If the PD pin is open (unterminated) the device will default to the enabled state.
13, 14, 15, 16	V _{S-}	Negative amplifier power supply input

SPECIFICATIONS; $V_{S+} - V_{S-} = 5\text{ V}$:

Test conditions unless otherwise noted: $V_{S+} = +2.5\text{ V}$, $V_{S-} = -2.5\text{ V}$, $G = 0\text{ dB}$, $\text{CM} = \text{open}$, $V_O = 2\text{ V}_{PP}$, $R_F = 499\ \Omega$, $R_L = 200\ \Omega$ Differential, $T_A = 25^\circ\text{C}$ Single-Ended Input, Differential Output, Input and Output Referenced to mid-supply

PARAMETER	TEST CONDITIONS		MIN	TYP	MAX	UNIT	TEST LEVEL ⁽¹⁾
AC PERFORMANCE							
Small-Signal Bandwidth	G = 0 dB, V _O = 100 mV _{PP}			620		MHz	C
	G = 6 dB, V _O = 100 mV _{PP}			450		MHz	
	G = 10 dB, V _O = 100 mV _{PP}			330		MHz	
	G = 20 dB, V _O = 100 mV _{PP}			120		MHz	
Gain-Bandwidth Product	G = 20 dB			1200		MHz	
Bandwidth for 0.1 dB flatness	G = 10 dB, V _O = 2 V _{PP}			30		MHz	
Large-Signal Bandwidth	G = 10 dB, V _O = 2 V _{PP}			132		MHz	
Slew Rate (Differential)	2-V Step			570		V/μs	
Rise Time				4	ns		
Fall Time				4			
Settling Time to 1%				6.2			
Settling Time to 0.1%				7			
2 nd Order Harmonic Distortion	f = 100 kHz, R _L = 1 kΩ	V _{OD} = 8 V _{PP}		−115		dBc	
3 rd Order Harmonic Distortion	f = 100 kHz, R _L = 1 kΩ	V _{OD} = 8 V _{PP}		−123		dBc	
3 rd Order Intermodulation Distortion	1-kHz Tone Spacing, R _L = 1 kΩ, V _{OD} = 4 V _{PP} /Tone	f _C = 100 kHz		−135		dBc	
Input Voltage Noise	f > 10 kHz			2		nV/√Hz	
Input Current Noise	f > 10 kHz			2		pA/√Hz	
DC PERFORMANCE							
Open-Loop Voltage Gain (A _{OL})				112		dB	C
Input Offset Voltage	T _A = 25°C			±0.25	±2.5	mV	A
	T _A = −40°C to 85°C			±0.25	±3	mV	
Input Bias Current	T _A = 25°C			6.5	10	μA	A
	T _A = −40°C to 85°C			6.4	11		
Input Offset Current	T _A = 25°C			±0.2	±2.5	μA	A
	T _A = −40°C to 85°C			±0.2	±3		
INPUT							
Common-Mode Input Range High				1.75		V	B
Common-Mode Input Range Low				-1.3			
Common-Mode Rejection Ratio				84		dB	

(1) Test levels: (A) 100% tested at 25°C . Overtemperature limits by characterization and simulation. (B) Limits set by characterization and simulation. (C) Typical value only for information.

SPECIFICATIONS; $V_{S+} - V_{S-} = 5\text{ V}$: (continued)

Test conditions unless otherwise noted: $V_{S+} = +2.5\text{ V}$, $V_{S-} = -2.5\text{ V}$, $G = 0\text{ dB}$, $CM = \text{open}$, $V_O = 2\text{ V}_{PP}$, $R_F = 499\ \Omega$, $R_L = 200\ \Omega$ Differential, $T_A = 25^\circ\text{C}$ Single-Ended Input, Differential Output, Input and Output Referenced to mid-supply

PARAMETER	TEST CONDITIONS		MIN	TYP	MAX	UNIT	TEST LEVEL ⁽¹⁾
OUTPUT							
Maximum Output Voltage High	Each output with 100 Ω to mid-supply	T _A = 25°C	1.95	2.16		V	A
		T _A = −40°C to 85°C	1.9	2.16			
Minimum Output Voltage Low		T _A = 25°C		−2.16	−1.95	V	
		T _A = −40°C to 85°C		−2.16	−1.9		
Differential Output Voltage Swing	T _A = −40°C to 85°C		7.8	8.64		V	C
Differential Output Current Drive	R _L = 10 Ω			105		mA	
Output Balance Error	V _O = 100 mV, f = 1 MHz			−80		dB	
OUTPUT COMMON-MODE VOLTAGE CONTROL							
Small-Signal Bandwidth				230		MHz	C
Gain				1		V/V	
Output Common-Mode Offset from CM input	1.25 V < CM < 3.5 V			±0.25		mV	
CM Input Bias Current	1.25 V < CM < 3.5 V			0.6		μA	
CM Input Voltage			−1.5		1.5	V	
CM Default Voltage	CM = 0.5 (V _{S+} + V _{S−})			0		V	
POWER SUPPLY							
Specified Operating Voltage			3	5	5.25	V	C
Maximum Quiescent Current	T _A = 25°C			14.2	15.3	mA	A
	T _A = −40°C to 85°C			14.2	15.5		
Minimum Quiescent Current	T _A = 25°C		13.1	14.2		mA	
	T _A = −40°C to 85°C		12.75	14.2			
Power Supply Rejection (±PSRR)				94		dB	C
POWERDOWN							
Referenced to V _{S−}							
Enable Voltage Threshold	For additional information, see the <i>Application Information</i> section of this data sheet.			>1.5		V	C
Disable Voltage Threshold				<−1.5		V	
Powerdown Quiescent Current	T _A = 25°C			15	70	μA	A
	T _A = −40°C to 85°C			15	75		

SPECIFICATIONS; $V_{S+} - V_{S-} = 3.3\text{ V}$:

Test conditions unless otherwise noted: $V_{S+} = +1.65\text{ V}$, $V_{S-} = -1.65\text{ V}$, $G = 0\text{ dB}$, $CM = \text{open}$, $V_O = 1\text{ V}_{PP}$, $R_F = 499\ \Omega$, $R_L = 200\ \Omega$ Differential, $T_A = 25^\circ\text{C}$ Single-Ended Input, Differential Output, Input and Output Referenced to mid-supply

PARAMETER	TEST CONDITIONS	TYP	UNIT	TEST LEVEL ⁽¹⁾
AC PERFORMANCE				
Small-Signal Bandwidth	G = 0 dB, V _O = 100 mV _{PP}	600	MHz	C
	G = 6 dB, V _O = 100 mV _{PP}	400	MHz	
	G = 10 dB, V _O = 100 mV _{PP}	310	MHz	
	G = 20 dB, V _O = 100 mV _{PP}	120	MHz	
Gain-Bandwidth Product	G = 20 dB	1200	MHz	
Bandwidth for 0.1-dB flatness	G = 6 dB, V _O = 1 V _{PP}	30	MHz	
Large-Signal Bandwidth	G = 6 dB, V _O = 1 V _{PP}		GHz	
Slew Rate (Differential)	2-V Step	520	V/μs	
Rise Time		4	ns	
Fall Time		4		
Settling Time to 1%		6.6		
Settling Time to 0.1%		7.1		
2 nd Order Harmonic Distortion		f = 100 kHz, V _{OD} = 4 V _{PP} , R _L = 1 kΩ	−135	
3 rd Order Harmonic Distortion	f = 100 kHz, V _{OD} = 4 V _{PP} , R _L = 1 kΩ	−146	dBc	
Input Voltage Noise	f > 10 kHz	2	nV/√Hz	
Input Current Noise	f > 10 kHz	2	pA/√Hz	
DC PERFORMANCE				
Open-Loop Voltage Gain (A _{OL})		104	dB	C
Input Offset Voltage	T _A = 25°C	±0.25	mV	
Input Bias Current	T _A = 25°C	6.5	μA	
Input Offset Current	T _A = 25°C	±0.2	μA	
INPUT				
Common-Mode Input Range High		1.4	V	C
Common-Mode Input Range Low		-0.45		
Common-Mode Rejection Ratio		84	dB	

- (1) Test levels: (A) 100% tested at 25°C . Overtemperature limits by characterization and simulation. (B) Limits set by characterization and simulation. (C) Typical value only for information.

SPECIFICATIONS; $V_{S+} - V_{S-} = 3.3\text{ V}$: (continued)

Test conditions unless otherwise noted: $V_{S+} = +1.65\text{ V}$, $V_{S-} = -1.65\text{ V}$, $G = 0\text{ dB}$, $CM = \text{open}$, $V_O = 1\text{ V}_{PP}$, $R_F = 499\ \Omega$, $R_L = 200\ \Omega$ Differential, $T_A = 25^\circ\text{C}$ Single-Ended Input, Differential Output, Input and Output Referenced to mid-supply

PARAMETER	TEST CONDITIONS		TYP	UNIT	TEST LEVEL ⁽¹⁾
OUTPUT					
Maximum Output Voltage High	Each output with 100 Ω to mid-supply	T _A = 25°C	1.4	V	C
Minimum Output Voltage Low		T _A = 25°C	-1.4	V	
Differential Output Voltage Swing			5.6	V	
Differential Output Current Drive	R _L = 10 Ω		78	mA	
Output Balance Error	V _O = 100 mV, f = 1 MHz		−80	dB	
OUTPUT COMMON-MODE VOLTAGE CONTROL					
Small-Signal Bandwidth			224	MHz	C
Gain			1	V/V	
Output Common-Mode Offset from CM input	1.25 V < CM < 3.5 V		±0.25	mV	
CM Input Bias Current	1.25 V < CM < 3.5 V		0.6	μA	
CM Default Voltage	CM = 0.5 (V _{S+} + V _{S-})		0	V	
POWER SUPPLY					
Specified Operating Voltage	T _A = 25°C		3.3	V	C
Quiescent Current			13	mA	
Power Supply Rejection (±PSRR)			94	dB	
POWERDOWN					
	Referenced to V _{S−}				
Enable Voltage Threshold	For additional information, see the <i>Application Information</i> section of this data sheet.		>1	V	C
Disable Voltage Threshold			<-1	V	
Powerdown Quiescent Current			10	μA	

TYPICAL CHARACTERISTICS

TYPICAL AC PERFORMANCE: $V_{S+} - V_{S-} = 5\text{ V}$

Test conditions unless otherwise noted: $V_{S+} = +2.5\text{ V}$, $V_{S-} = -2.5\text{ V}$, CM = open, $V_O = 2\text{ V}_{PP}$, $R_F = 499\ \Omega$, $R_L = 200\ \Omega$
Differential, G = 0 dB, Single-Ended Input, Input and Output Referenced to Midrail

Small-Signal Frequency Response		Figure 1
Large Signal Frequency Response		Figure 2
0.1 dB Flatness		Figure 3
S-Parameters	vs Frequency	Figure 4
Transition Rate	vs Output Voltage	Figure 5
Transient Response		Figure 6
		Figure 7
Output Voltage Swing	vs Load Resistance	Figure 8
Input Offset Voltage	vs Input Common-Mode Voltage	Figure 9
Input Bias Current	vs Supply Voltage	Figure 10
Open Loop Gain	vs Frequency	Figure 11
Input Referred Noise	vs Frequency	Figure 12
Quiescent Current	vs Supply Voltage	Figure 13
Power Supply Current	vs Supply Voltage in Powerdown Mode	Figure 14
Output Balance Error	vs Frequency	Figure 15
CM Small-Signal Frequency Response		Figure 16
CM Input Bias Current	vs CM Input Voltage	Figure 17
Differential Output Offset Voltage	vs CM Input Voltage	Figure 18
Output Common-Mode Offset	vs CM Input Voltage	Figure 19

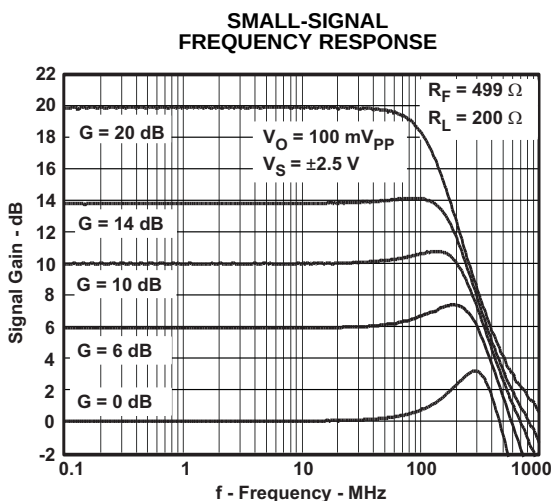


Figure 1.

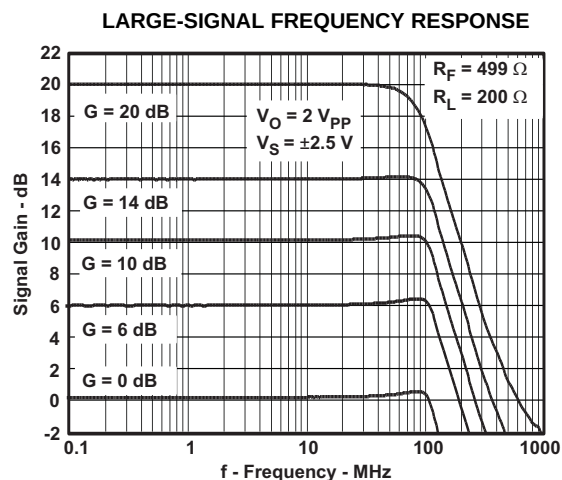


Figure 2.

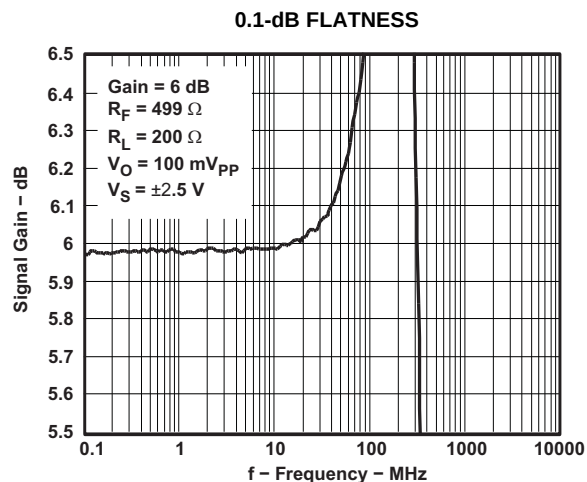


Figure 3.

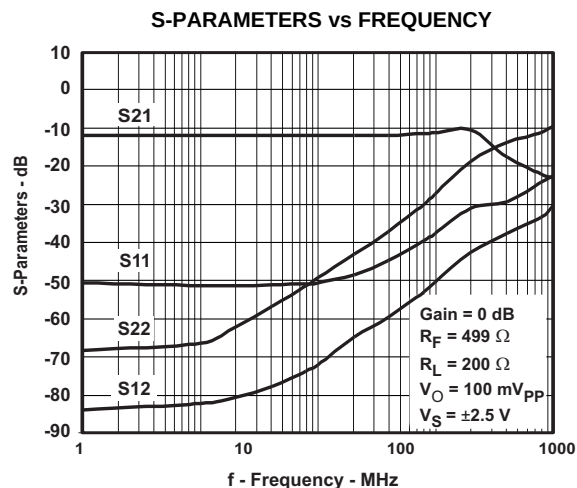


Figure 4.

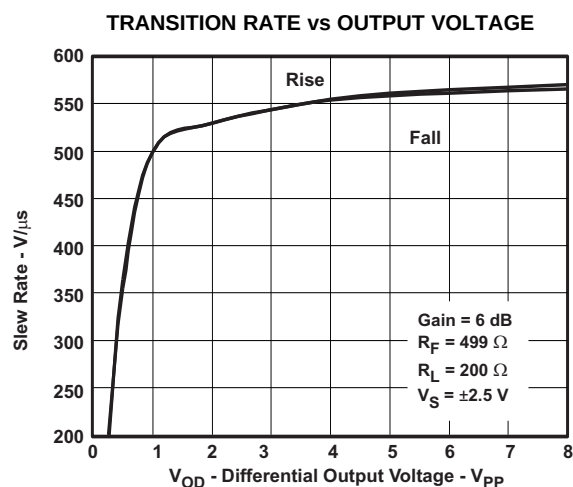


Figure 5.

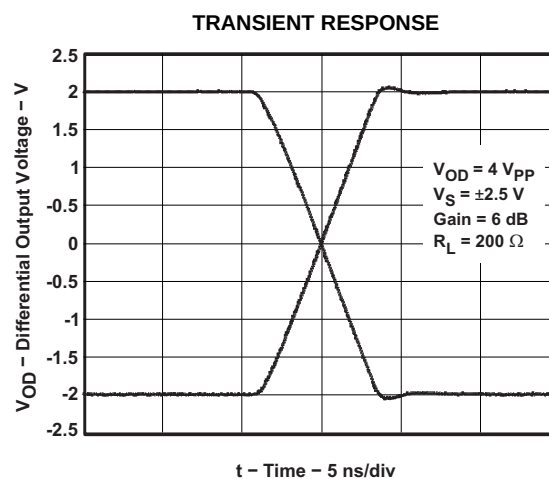


Figure 6.

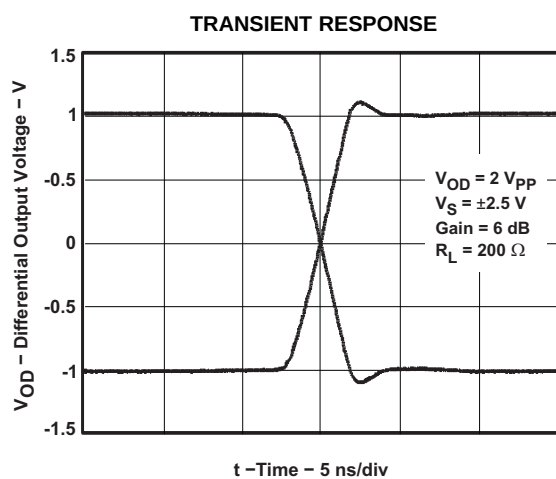


Figure 7.

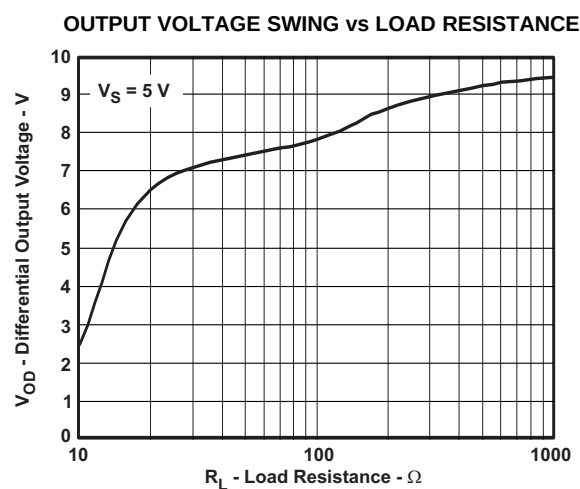


Figure 8.

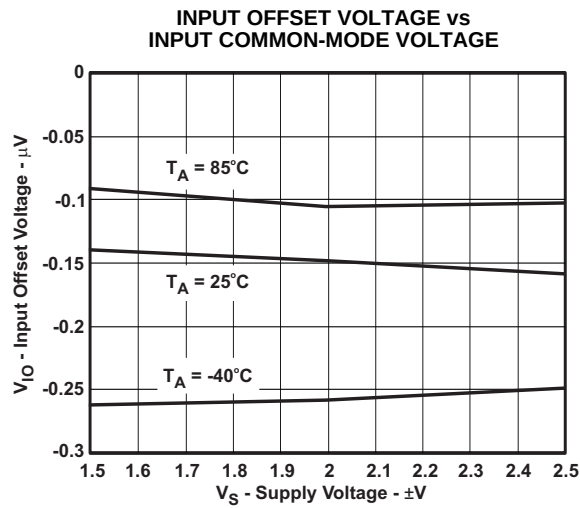


Figure 9.

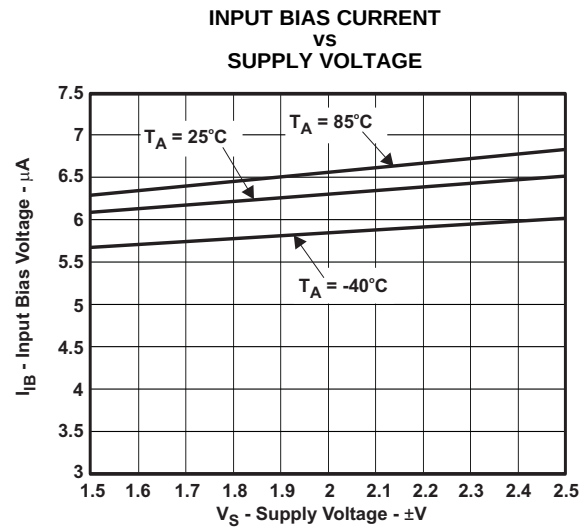


Figure 10.

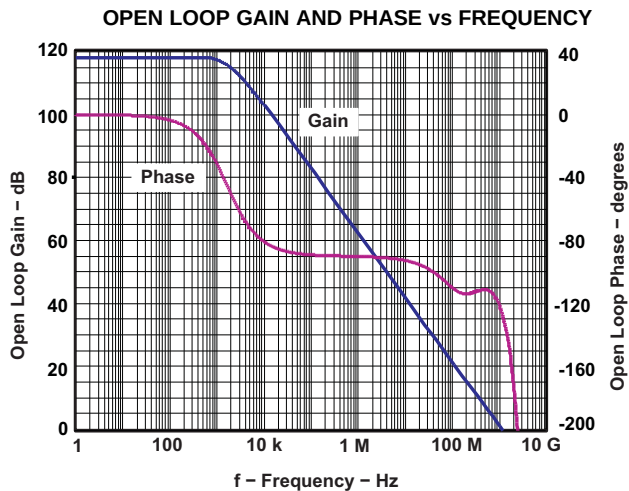


Figure 11.

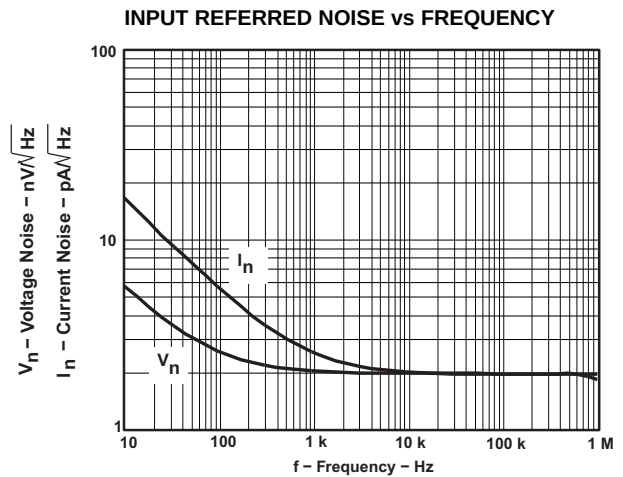


Figure 12.

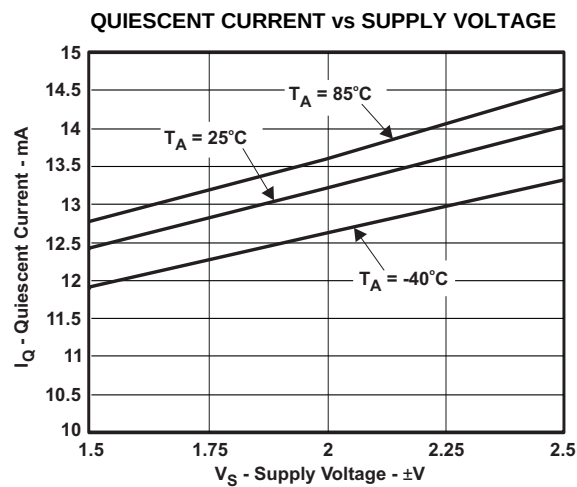


Figure 13.

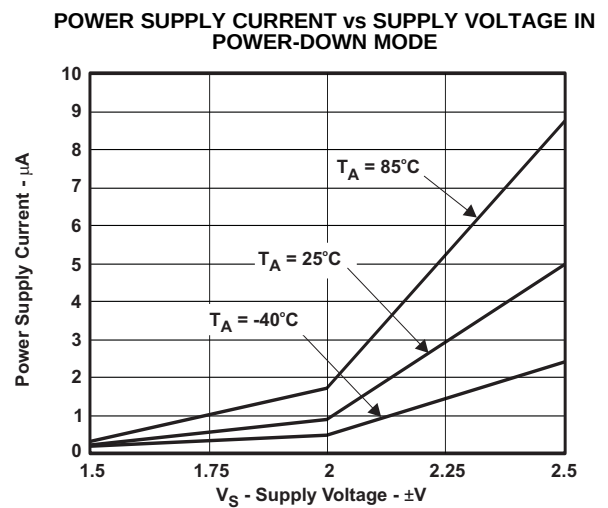


Figure 14.

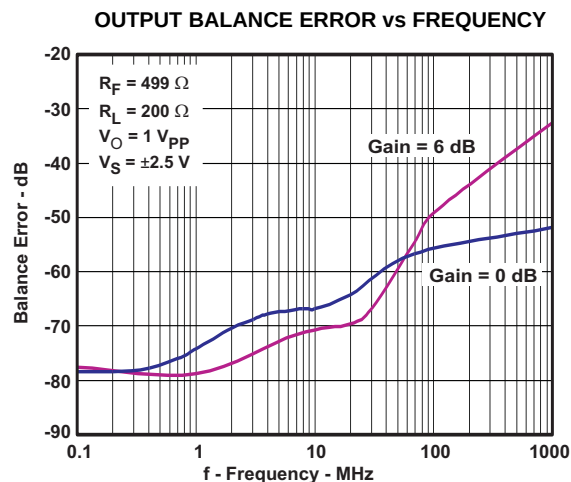


Figure 15.

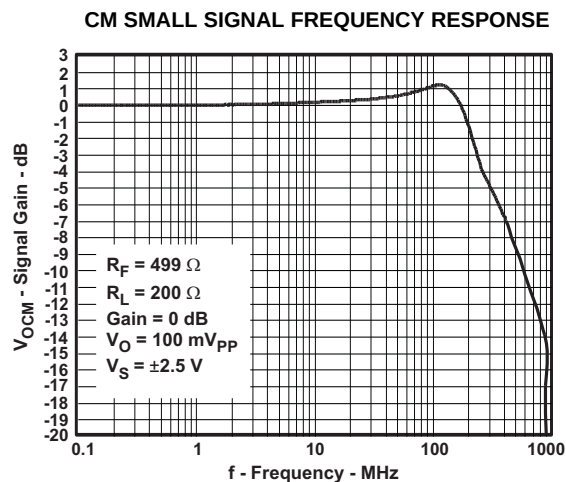


Figure 16.

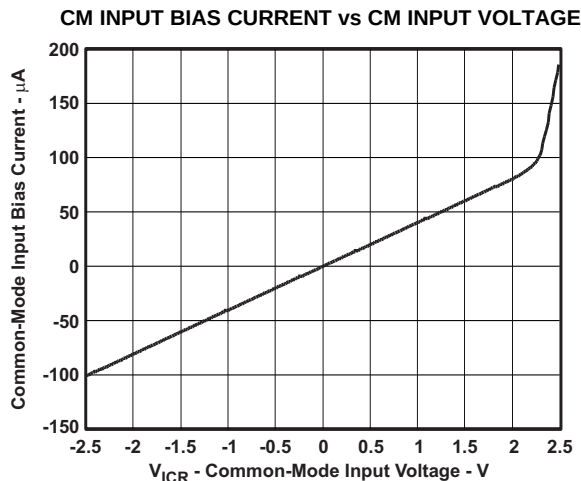


Figure 17.

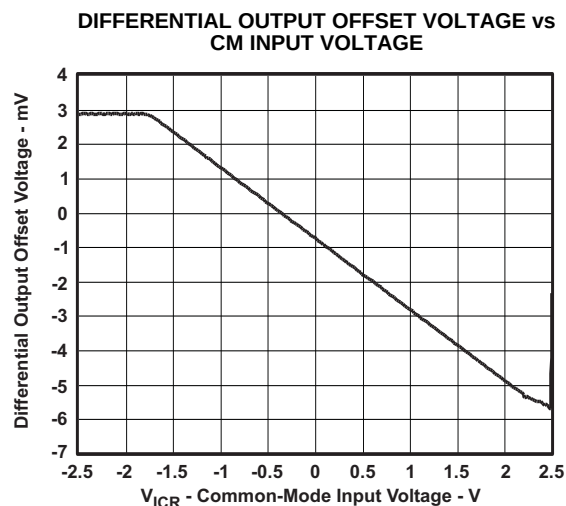


Figure 18.

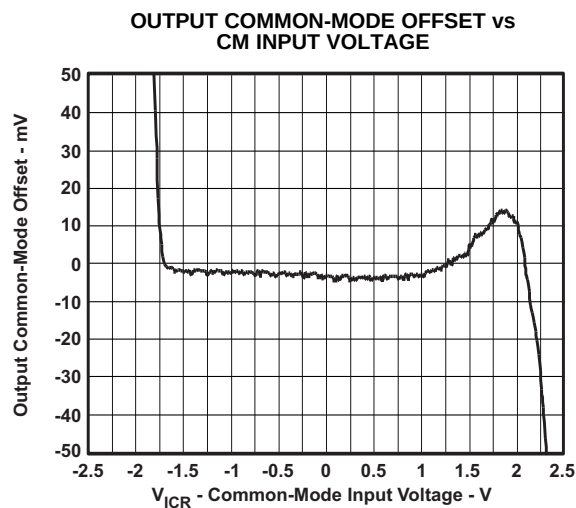


Figure 19.

TYPICAL AC PERFORMANCE: $V_{S+} - V_{S-} = 3.3\text{ V}$

Test conditions unless otherwise noted: $V_{S+} = 1.65\text{ V}$, $V_{S-} = -1.65\text{ V}$, CM = open, $V_{OD} = 1\text{ V}_{PP}$, $R_F = 499\ \Omega$, $R_L = 200\ \Omega$ Differential, G = 0 dB, Single-Ended Input, Input and Output Referenced to Midrail

Small-Signal Frequency Response		Figure 20
Large Signal Frequency Response		Figure 21
0.1 dB Flatness		Figure 22
S-Parameters	vs Frequency	Figure 23
Transition Rate	vs Output Voltage	Figure 24
Transient Response		Figure 25
		Figure 26
Output Balance Error	vs Frequency	Figure 27
CM Input Impedance	vs Frequency	Figure 28

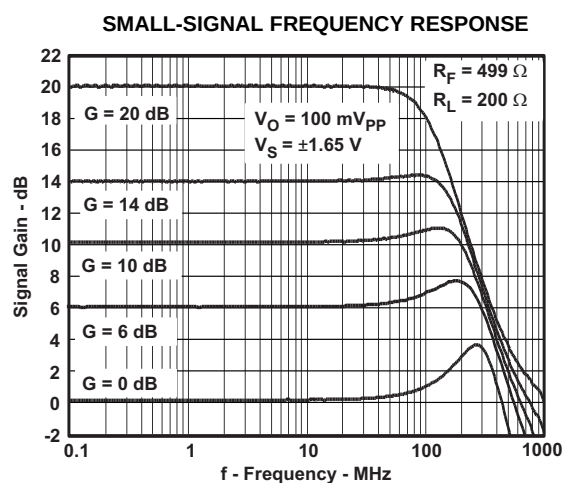


Figure 20.

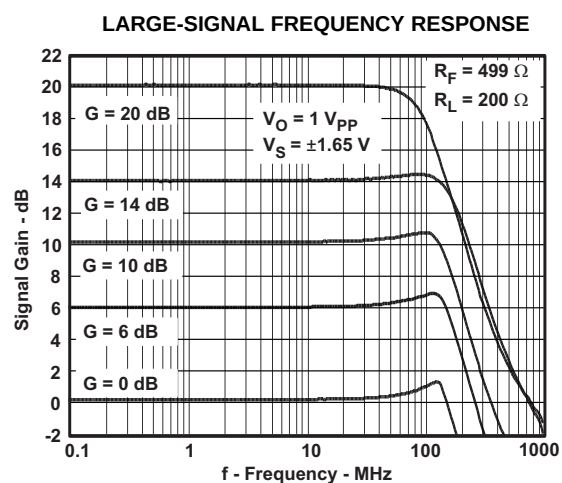


Figure 21.

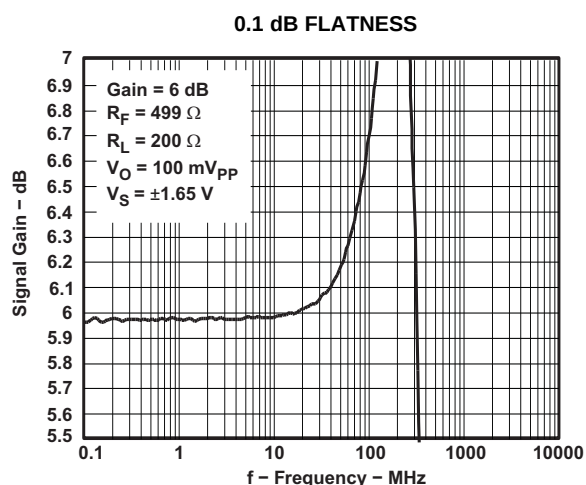


Figure 22.

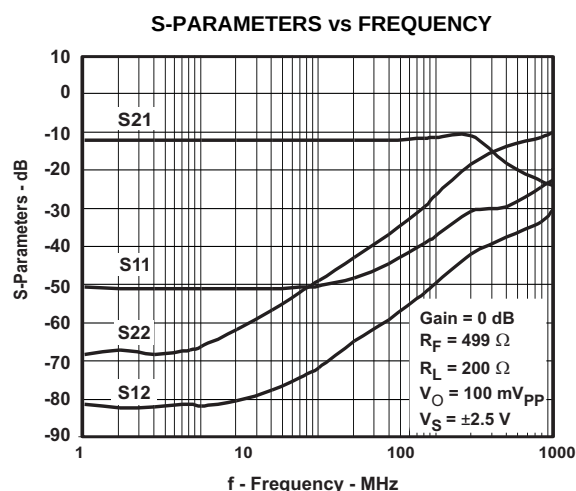


Figure 23.

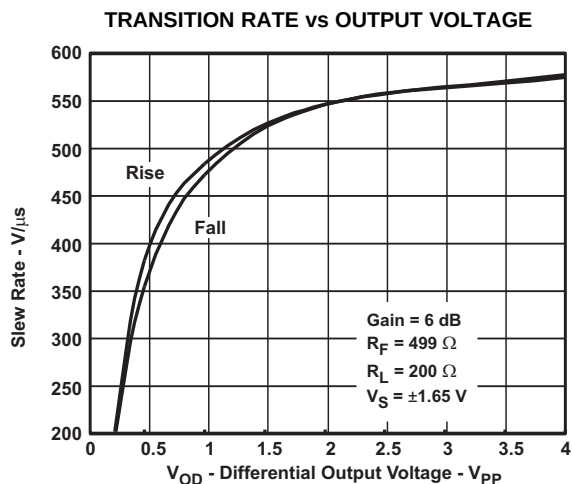


Figure 24.

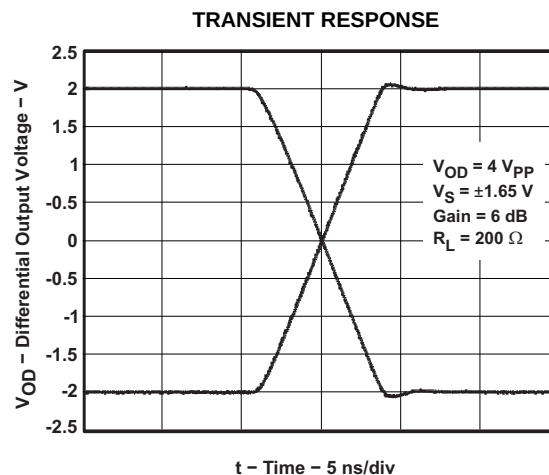


Figure 25.

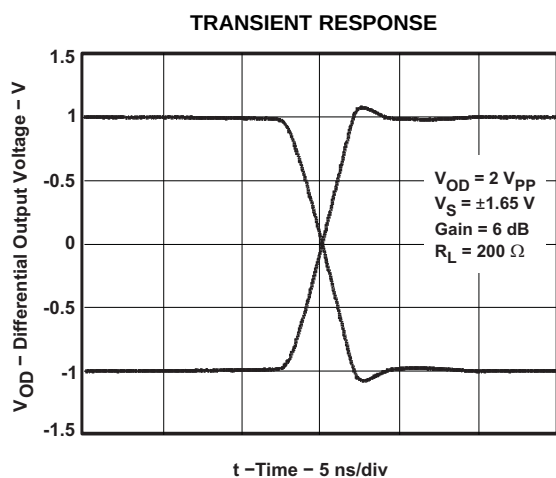


Figure 26.

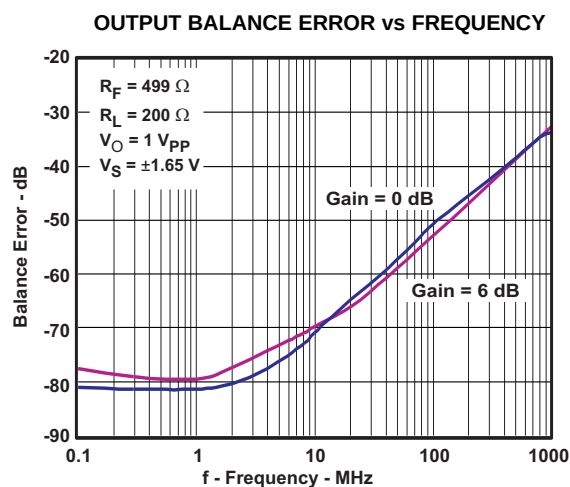


Figure 27.

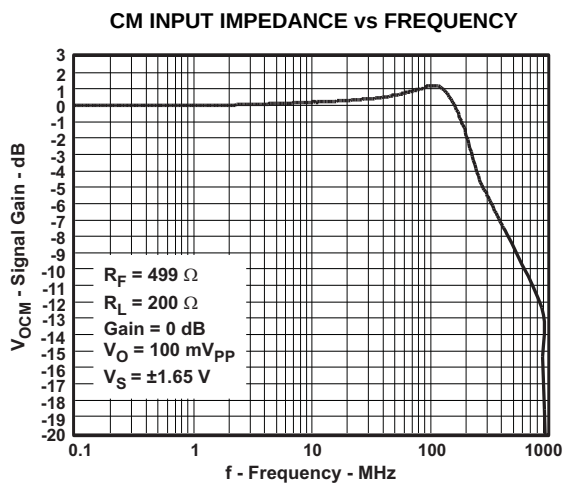


Figure 28.

TEST CIRCUITS

The THS4520 is tested with the following test circuits built on the EVM. For simplicity, power supply decoupling is not shown – see layout in the applications section for recommendations.

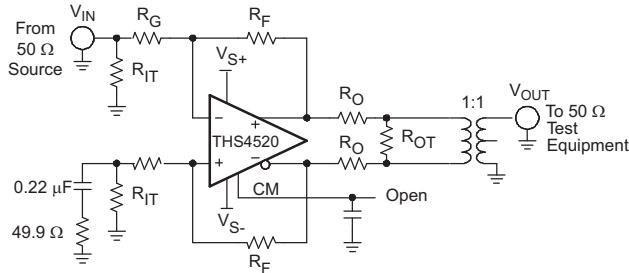


Figure 29. General Test Circuit for Device Testing and Characterization

Depending on the test conditions, component values are changed per the following tables, or as otherwise noted. The signal generators used are ac coupled 50-Ω sources and a 0.22-μF capacitor and a 49.9-Ω resistor to ground are inserted across R_{IT} on the alternate input to balance the circuit. A split power supply is used to ease the interface to common test equipment, but the amplifier can be operated single-supply as described in the applications section with no impact on performance.

Table 1. Gain Component Values

GAIN	R_F	R_G	R_{IT}
0 dB	499 Ω	487 Ω	53.6 Ω
6 dB	499 Ω	243 Ω	57.6 Ω
10 dB	499 Ω	147 Ω	63.4 Ω
14 dB	499 Ω	88.7 Ω	71.5 Ω
20 dB	499 Ω	34.8 Ω	115 Ω

Note: The gain setting includes 50-Ω source impedance. Components are chosen to achieve gain and 50-Ω input termination.

Table 2. Load Component Values

R_L	R_O	R_{OT}	Atten.
100 Ω	25 Ω	open	6 dB
200 Ω	86.6 Ω	69.8 Ω	16.8 dB
499 Ω	237 Ω	56.2 Ω	25.5 dB
1 kΩ	487 Ω	52.3 Ω	31.8 dB

Note: The total load includes 50-Ω termination by the test equipment. Components are chosen to achieve load and 50-Ω line termination through a 1:1 transformer.

Due to the voltage divider on the output formed by the load component values, the amplifier's output is attenuated in test. The column *Atten* in Table 2 shows the attenuation expected from the resistor divider. When using a transformer at the output the signal will have slightly more loss, and the numbers will be approximate.

Frequency Response

The general circuit shown in Figure 29 is modified as shown in Figure 30, and is used to measure the frequency response of the device.

A network analyzer is used as the signal source and as the measurement device. The output impedance of the network analyzer is 50 Ω. R_{IT} and R_G are chosen to impedance match to 50 Ω, and to maintain the proper gain. To balance the amplifier, a 0.22-μF capacitor and 49.9-Ω resistor to ground are inserted across R_{IT} on the alternate input.

The output is probed using a high-impedance differential probe across the 100-Ω resistor. The gain is referred to the amplifier output by adding back the 6-dB loss due to the voltage divider on the output.

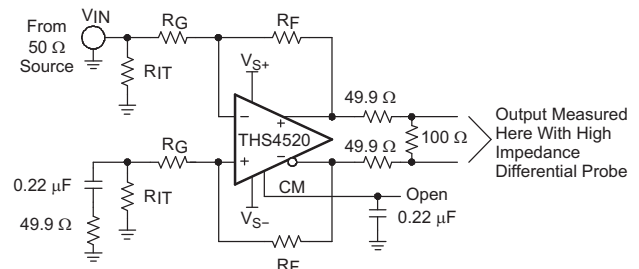


Figure 30. Frequency Response Test Circuit

S-Parameter, Slew Rate, Transient Response, Settling Time, Output Voltage

The circuit shown in Figure 31 is used to measure s-parameters, slew rate, transient response, settling time, and output voltage swing.

Because S21 is measured single-ended at the load with 50-Ω double termination, add 12 dB to see the amplifier's output as a differential signal.

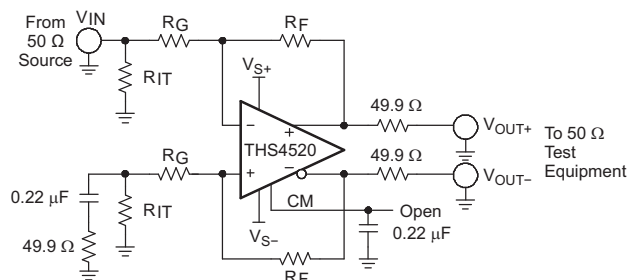


Figure 31. S-Parameter, SR, Transient Response, Settling Time, V_{OUT} Swing

CM Input

The circuit shown in Figure 32 is used to measure the frequency response of the CM input. Frequency response is measured single-ended at V_{OUT+} or V_{OUT-} with the input injected at V_{IN}, R_{CM} = 0 Ω and R_{CMT} = 49.9 Ω.

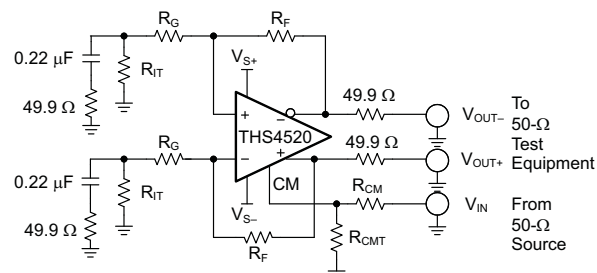


Figure 32. CM Input Test Circuit

APPLICATION INFORMATION

APPLICATIONS

The following circuits show application information for the THS4520. For simplicity, power supply decoupling capacitors are not shown in these diagrams. For more detail on the use and operation of fully differential op amps see application report *Fully-Differential Amplifiers* (SLOA054).

Differential Input to Differential Output Amplifier

The THS4520 is a fully differential op amp, and can be used to amplify differential input signals to differential output signals. A basic block diagram of the circuit is shown in Figure 33 (CM input not shown). The gain of the circuit is set by R_F divided by R_G .

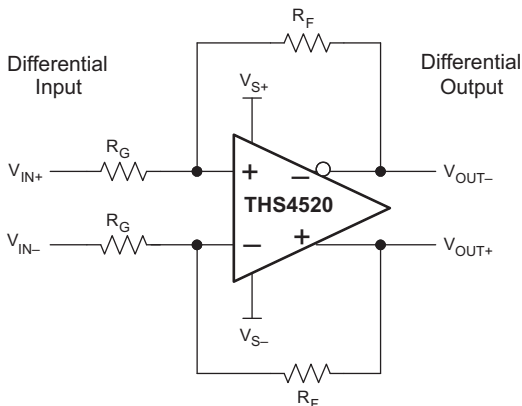


Figure 33. Differential Input to Differential Output Amplifier

Depending on the source and load, input and output termination can be accomplished by adding R_{IT} and R_O .

Single-Ended Input to Differential Output Amplifier

The THS4520 can be used to amplify and convert single-ended input signals to differential output signals. A basic block diagram of the circuit is shown in Figure 34 (CM input not shown). The gain of the circuit is again set by R_F divided by R_G .

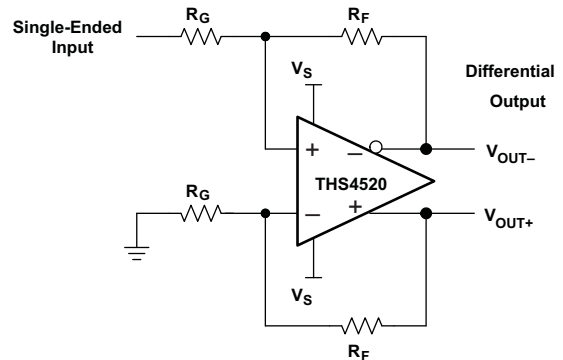


Figure 34. Single-Ended Input to Differential Output Amplifier

Input Common-Mode Voltage Range

The input common-mode voltage of a fully differential op amp is the voltage at the '+' and '-' input pins of the op amp.

It is important to not violate the input common-mode voltage range (V_{ICR}) of the op amp. Assuming the op amp is in linear operation, the differential voltage across the input pins is only a few millivolts at most. So finding the voltage at one input pin determines the input common-mode voltage of the op amp.

Treating the negative input as a summing node, the voltage is given by Equation 1:

$$V_{IC} = \left(V_{OUT+} \times \frac{R_G}{R_G + R_F} \right) + \left(V_{IN-} \times \frac{R_F}{R_G + R_F} \right) \quad (1)$$

To determine the V_{ICR} of the op amp, the voltage at the negative input is evaluated at the extremes of V_{OUT+} .

As the gain of the op amp increases, the input common-mode voltage becomes closer and closer to the input common-mode voltage of the source.

Setting the Output Common-Mode Voltage

The output common-mode voltage is set by the voltage at the CM pin(s). The internal common-mode control circuit maintains the output common-mode voltage within 0.25-mV offset (typical) from the set voltage, when set within ± 0.5 V of mid-supply. If left unconnected, the common-mode set point is set to mid-supply by internal circuitry, which may be over-driven from an external source. Figure 35 is representative of the CM input. The internal CM circuit has about 230 MHz of bandwidth, which is

required for best performance, but it is intended to be a DC bias input pin. Bypass capacitors are recommended on this pin to reduce noise at the output. The external current required to overdrive the internal resistor divider is given by Equation 2:

$$I_{EXT} = \frac{2V_{CM} - (V_{S+} - V_{S-})}{50\text{ k}\Omega} \quad (2)$$

where V_{CM} is the voltage applied to the CM pin.

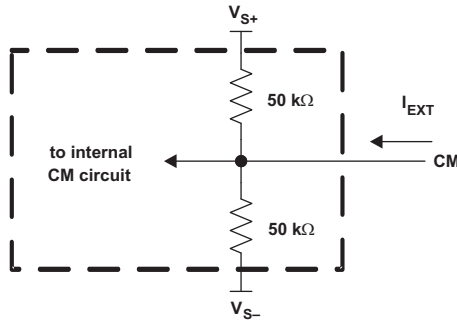


Figure 35. CM Input Circuit

Powerdown Operation: Device Enable/Disable Thresholds

The enable/disable thresholds of the THS4520 are dependent upon the power supplies, and the thresholds are always referenced to the lower power supply rail. The device is enabled or disabled for the following conditions:

- Device enabled: $V_{PD} > V_{S-} + 0.8 \times (V_{S+} - V_{S-})$
- Device disabled: $V_{PD} < V_{S-} + 0.2 \times (V_{S+} - V_{S-})$

If the $\overline{PD}$ pin is left open, the device will default to the enabled state.

Table 3 shows the thresholds for some common power supply configurations:

Table 3. Power Supply Configurations

Power Supply (V_{S+} , V_{S-})	Enable Threshold (V)	Disable Threshold (V)	Comment
$\pm 2.5\text{ V}$	1.5	-1.5	Shown in data table
$\pm 1.65\text{ V}$	1	-1	Shown in data table
(4 V, -1 V)	3	0	Split, unbalanced supplies
(5 V, gnd)	4	1	Single-sided supply
(3.3 V, gnd)	2.64	0.66	Single-sided supply
(3 V, gnd)	2.4	0.6	Single-sided supply

Single-Supply Operation (3 V to 5 V)

To facilitate testing with common lab equipment, the THS4520 EVM allows split-supply operation, and the characterization data presented in this data sheet was taken with split-supply power inputs. The device can easily be used with a single-supply power input without degrading the performance. Figure 36, Figure 37, and Figure 38 show DC and AC-coupled single-supply circuits with single-ended inputs. These configurations all allow the input and output common-mode voltage to be set to mid-supply allowing for optimum performance. The information presented here can also be applied to differential input sources.

In Figure 36, the source is referenced to the same voltage as the CM pin (V_{CM}). V_{CM} is set by the internal circuit to mid-supply. R_T along with the input impedance of the amplifier circuit provides input termination, which is also referenced to V_{CM} .

Note R_S and R_T are added to the alternate input from the signal input to balance the amplifier. Alternately, one resistor can be used equal to the combined value $R_G + R_S || R_T$ on this input. This is also true of the circuits shown in Figure 37 and Figure 38.

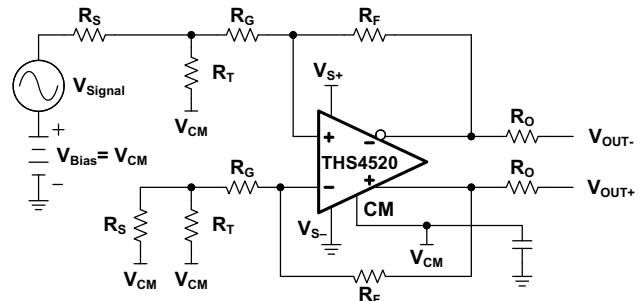


Figure 36. THS4520 DC Coupled Single-Supply with Input Biased to V_{CM}

In Figure 37 the source is referenced to ground and so is the input termination resistor. R_{PU} is added to the circuit to avoid violating the V_{ICR} of the op amp. The proper value of resistor to add can be calculated from Equation 3:

$$R_{PU} = \frac{(V_{IC} - V_{S+})}{V_{CM} \left(\frac{1}{R_F} \right) - V_{IC} \left(\frac{1}{R_{IN}} + \frac{1}{R_F} \right)} \quad (3)$$

V_{IC} is the desired input common-mode voltage, $V_{CM} = CM$, and $R_{IN} = R_G + R_S || R_T$. To set to mid-supply, make the value of $R_{PU} = R_G + R_S || R_T$.

Table 4 is a modification of Table 1 to add the proper values with R_{PU} assuming a 50-Ω source impedance and setting the input and output common-mode voltage to mid-supply.

There are two drawbacks to this configuration. One is it requires additional current from the power supply. Using the values shown for a gain of 0 dB requires 10 mA more current with 5-V supply, and 6.5 mA more current with 3.3-V supply.

The other drawback is this configuration also increases the noise gain of the circuit. In the 10-dB gain case, noise gain increases by a factor of 1.7.

Table 4. RPU Values for Various Gains

Gain	R _F	R _G	R _{IT}	R _{PU}
0 dB	499 Ω	487 Ω	54.9 Ω	511 Ω
6 dB	499 Ω	243 Ω	59 Ω	270 Ω
10 dB	499 Ω	150 Ω	68.1 Ω	178 Ω
14 dB	499 Ω	93.1 Ω	82.5 Ω	124 Ω
20 dB	499 Ω	40.2 Ω	221 Ω	80.6 Ω

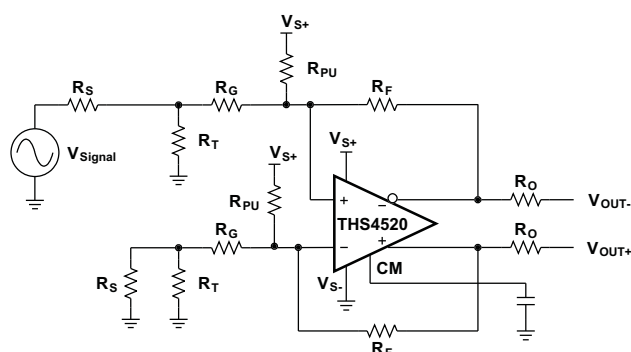


Figure 37. THS4520 DC Coupled Single-Supply with R_{PU} Used to Set V_{IC}

Figure 38 shows AC coupling to the source. Using capacitors in series with the termination resistors allows the amplifier to self-bias both input and output to mid-supply.

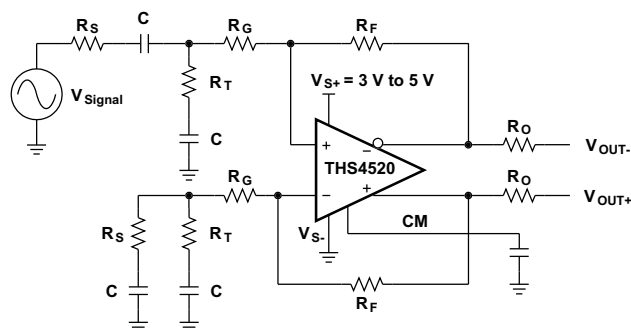


Figure 38. THS4520 AC Coupled Single-Supply

Layout Recommendations

It is recommended to follow the layout of the external components near the amplifier, ground plane construction, and power routing of the EVM as closely as possible. General guidelines are:

1. Signal routing should be direct and as short as possible into and out of the op amp circuit.
2. The feedback path should be short and direct avoiding vias.
3. Ground or power planes should be removed from directly under the amplifier's input and output pins.
4. An output resistor is recommended on each output, as near to the output pin as possible.
5. Two 10- μ F and two 0.1- μ F power-supply decoupling capacitors should be placed as near to the power-supply pins as possible.
6. Two 0.1- μ F capacitors should be placed between the CM input pins and ground. This limits noise coupled into the pins. One each should be placed to ground near pin 4 and pin 9.
7. It is recommended to split the ground plane on layer 2 (L2) as shown below and to use a solid ground on layer 3 (L3). A single-point connection should be used between each split section on L2 and L3.
8. A single-point connection to ground on L2 is recommended for the input termination resistors R1 and R2. This should be applied to the input gain resistors if termination is not used.
9. The THS4520 recommended PCB footprint is shown in [Figure 39](#).

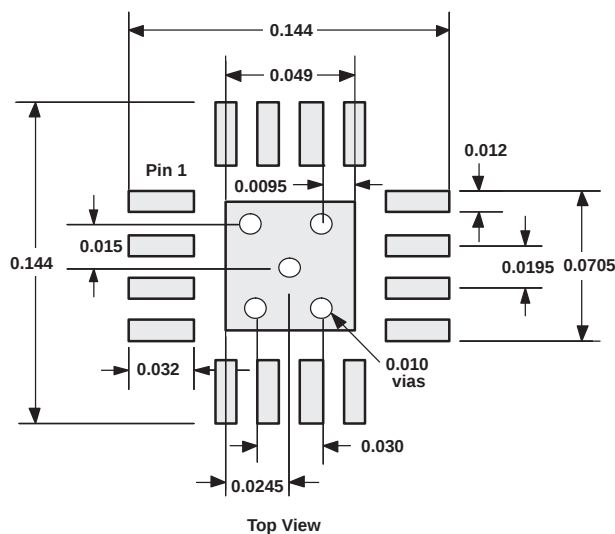


Figure 39. QFN Etch and Via Pattern

THS4520 EVM

Figure 40 is the THS4520 EVAL1 EVM schematic, layers 1 through 4 of the PCB are shown Figure 41, and Table 5 is the bill of material for the EVM as supplied from TI.

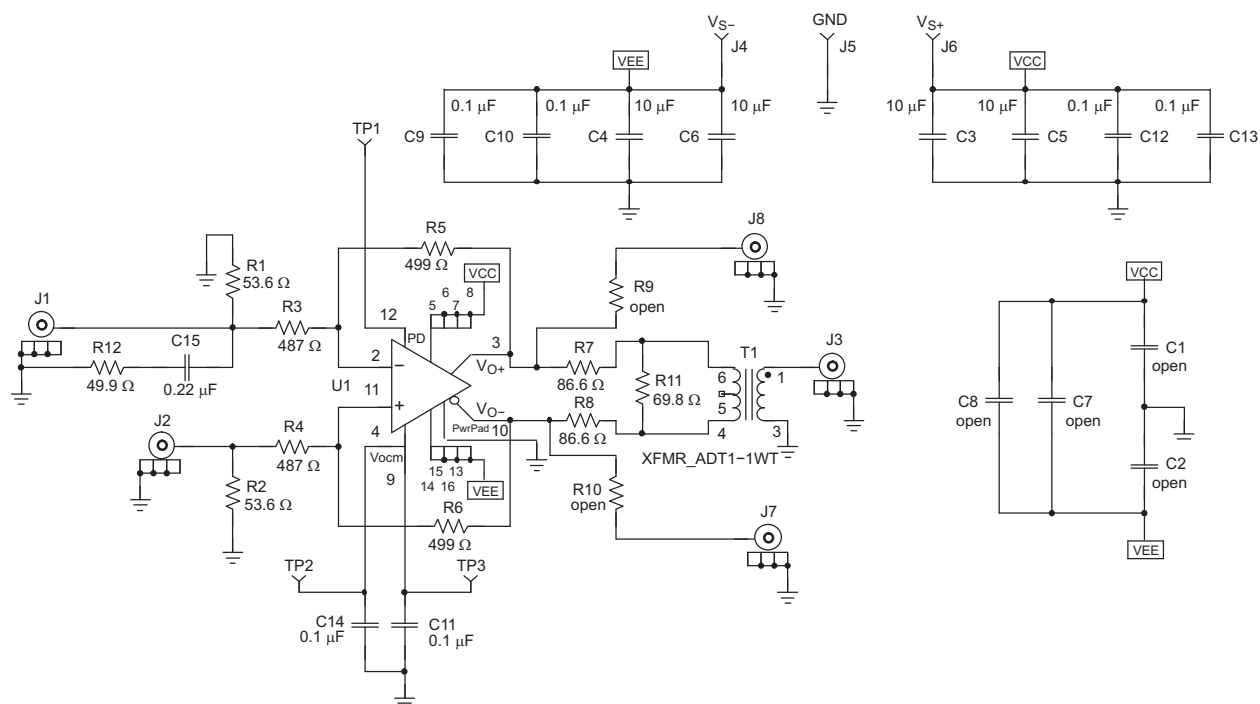


Figure 40. THS4520 EVAL1 EVM Schematic

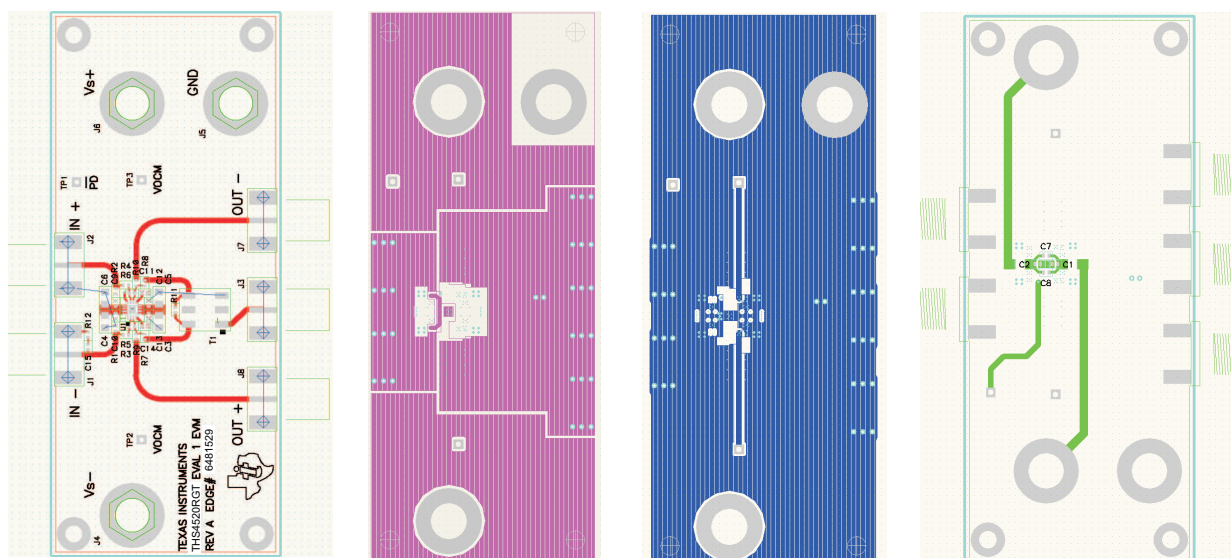


Figure 41. THS4520 EVAL1 EVM Layer 1 through 4

Table 5. THS4520 EVAL1 EVM Bill of Materials

ITEM	DESCRIPTION	SMD SIZE	REFERENCE DESIGNATOR	PCB QTY	MANUFACTURER'S PART NUMBER
1	CAP, 10.0 μ F, Ceramic, X5R, 6.3V	0805	C3, C4, C5, C6	4	(AVX) 08056D106KAT2A
2	CAP, 0.1 μ F, Ceramic, X5R, 10V	0402	C9, C10, C11, C12, C13, C14	6	(AVX) 0402ZD104KAT2A
3	CAP, 0.22 Ω F, Ceramic, X5R, 6.3V	0402	C15	1	(AVX) 04026D224KAT2A
4	OPEN	0402	C1, C2, C7, C8	4	
5	OPEN	0402	R9, R10	2	
6	Resistor, 49.9 Ω , 1/16W, 1%	0402	R12	1	(KOA) RK73H1ETTP49R9F
7	Resistor, 53.6 Ω , 1/16W, 1%	0402	R1, R2	2	(KOA) RK73H1ETTP53R6F
8	Resistor, 69.8 Ω , 1/16W, 1%	0402	R11	1	(KOA) RK73H1ETTP69R8F
9	Resistor, 86.6 Ω , 1/16W, 1%	0402	R7, R8	2	(KOA) RK73H1ETTP86R6F
10	Resistor, 487 Ω , 1/16W, 1%	0402	R3, R4	2	(KOA) RK73H1ETTP4870F
11	Resistor, 499 Ω , 1/16W, 1%	0402	R5, R6	2	(KOA) RK73H1ETTP4990F
12	Transformer, RF		T1	1	(MINI-CIRCUITS) ADT1-1WT
13	Jack, banana receptance, 0.25" diameter hole		J4, J5, J6	3	(HH SMITH) 101
14	OPEN		J1, J7, J8	3	
15	Connector, edge, SMA PCB Jack		J2, J3	2	(JOHNSON) 142-0701-801
16	Test point, Red		TP1, TP2, TP3	3	(KEYSTONE) 5000
17	IC, THS4520		U1	1	(TI) THS4520RGT
18	Standoff, 4-40 HEX, 0.625" length			4	(KEYSTONE) 1808
19	SCREW, PHILLIPS, 4-40, 0.250"			4	SHR-0440-016-SN
20	Printed circuit board			1	(TI) EDGE# 6481529

EVM WARNINGS AND RESTRICTIONS

It is important to operate this EVM within the input voltage range of 3 V to 5 V and the output voltage range of 3 V to 5 V.

Exceeding the specified input range may cause unexpected operation and/or irreversible damage to the EVM. If there are questions concerning the input range, please contact a TI field representative prior to connecting the input power.

Applying loads outside of the specified output range may result in unintended operation and/or possible permanent damage to the EVM. Please consult the EVM User's Guide prior to connecting any load to the EVM output. If there is uncertainty as to the load specification, please contact a TI field representative.

During normal operation, some circuit components may have case temperatures greater than 85°C. The EVM is designed to operate properly with certain components above 85°C as long as the input and output ranges are maintained. These components include but are not limited to linear regulators, switching transistors, pass transistors, and current sense resistors. These types of devices can be identified using the EVM schematic located in the EVM User's Guide. When placing measurement probes near these devices during operation, please be aware that these devices may be very warm to the touch.

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PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
THS4520RGTR	ACTIVE	QFN	RGT	16	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
THS4520RGTRG4	ACTIVE	QFN	RGT	16	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
THS4520RGTT	ACTIVE	QFN	RGT	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
THS4520RGTTG4	ACTIVE	QFN	RGT	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

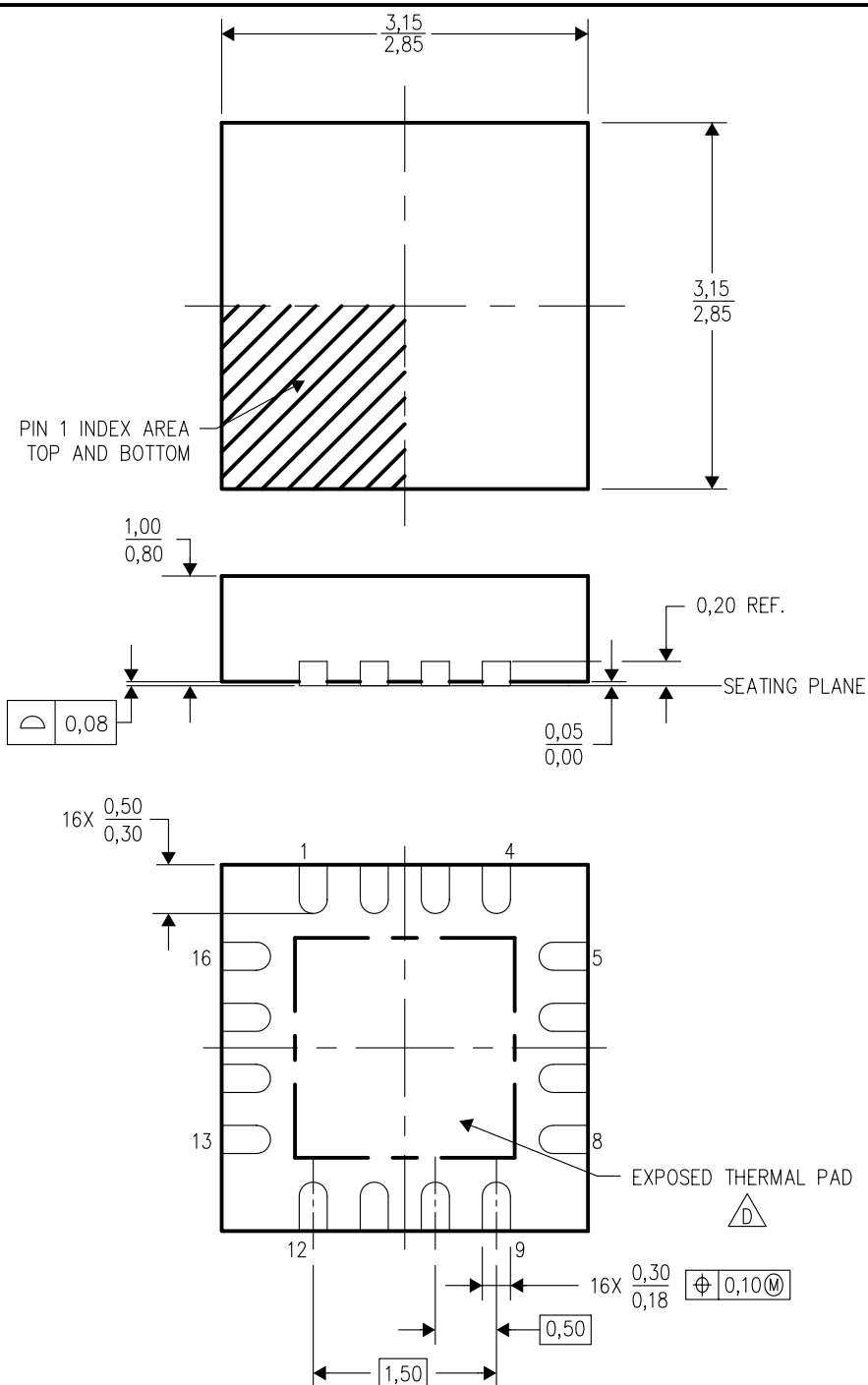
⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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RGT (S-PQFP-N16)

PLASTIC QUAD FLATPACK



4203495/E 11/04

- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
 - B. This drawing is subject to change without notice.
 - C. Quad Flatpack, No-leads (QFN) package configuration.
 - $\triangle D$ The package thermal pad must be soldered to the board for thermal and mechanical performance. See the Product Data Sheet for details regarding the exposed thermal pad dimensions.
 - E. Falls within JEDEC MO-220.

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